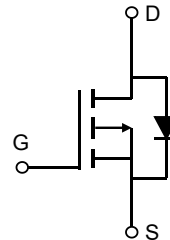


Description

Features

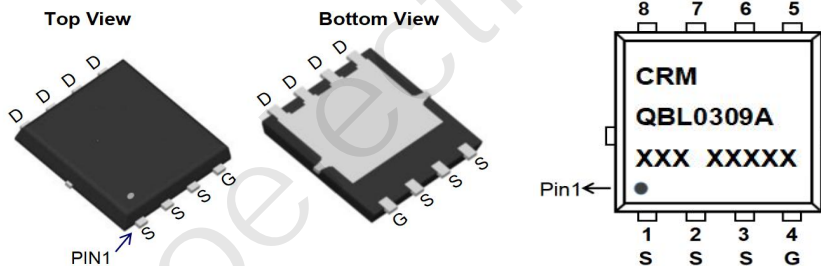
- -30V, -45A
 $R_{DS(ON)}$ Typ = 5.7mΩ @ $V_{GS} = -10V$
 $R_{DS(ON)}$ Typ = 9.7mΩ @ $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔV_d s TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMQBL0309A	CRMQBL0309A	PDFN3.3x3.3-8L	TAPING	13"	5000	50000

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	-30	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-45
		$T_C = 100^\circ C$	-27
I_{DM}	Pulsed Drain Current ⁽¹⁾	-180	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	110	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	26
$R_{\theta JC}$	Thermal Resistance, Junction to Case	4.8	$^\circ C/W$
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ C$

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = -250μA, V _{GS} = 0V	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V	-	-	-1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.6	-2.2	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = -10V, I _D = -15A	-	5.7	7.4	mΩ
		V _{GS} = -4.5V, I _D = -10A	-	9.7	12.6	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = -15V, f = 1MHz	-	2127	-	pF
C _{oss}	Output Capacitance		-	396	-	pF
C _{rss}	Reverse Transfer Capacitance		-	329	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to -10V V _{DS} = -15V, I _D = -5A	-	58	-	nC
Q _{gs}	Gate Source Charge		-	10	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	11	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = -10V, V _{DD} = -15V I _D = -10A, R _{GEN} = 5Ω	-	10	-	ns
t _r	Turn-On Rise Time		-	60	-	ns
t _{d(off)}	Turn-Off DelayTime		-	65	-	ns
t _f	Turn-Off Fall Time		-	50	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-45	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-180	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -10A	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	I _F = -10A, di/dt = 100A/us	-	17	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	8	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting T_J=25°C, V_{DD}=-15V, V_G=-10V, R_G=25ohm, L=0.5mH, I_{AS}=-21A
 3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

Test Circuit

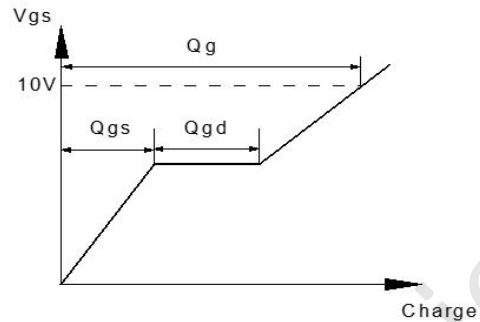
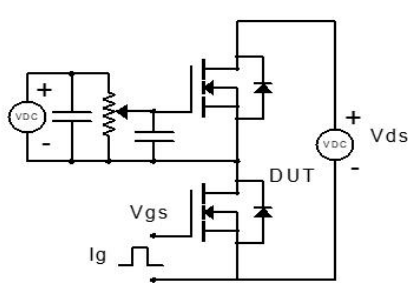


Figure 1: Gate Charge Test Circuit & Waveform

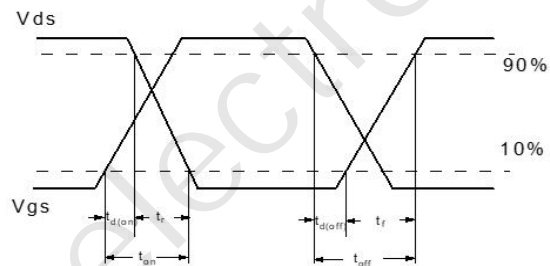
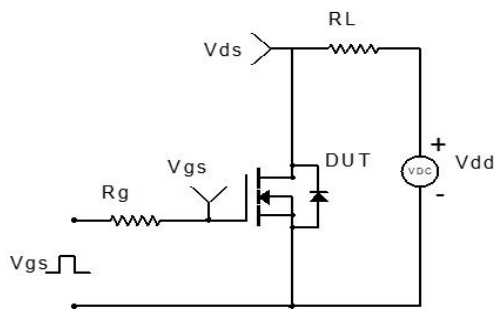


Figure 2: Resistive Switching Test Circuit & Waveform

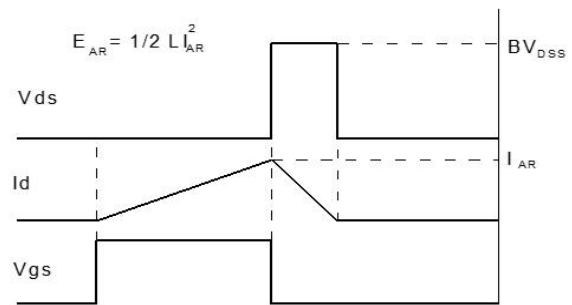
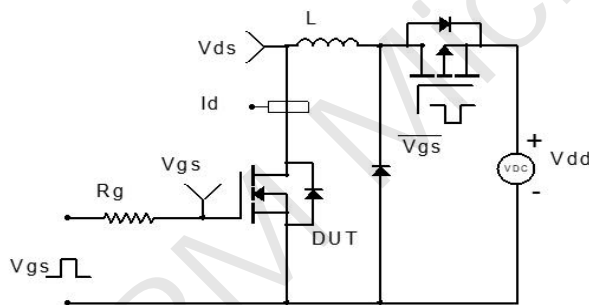


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

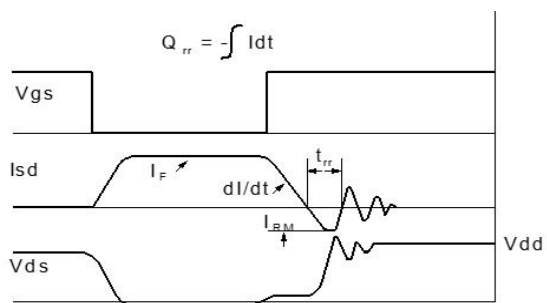
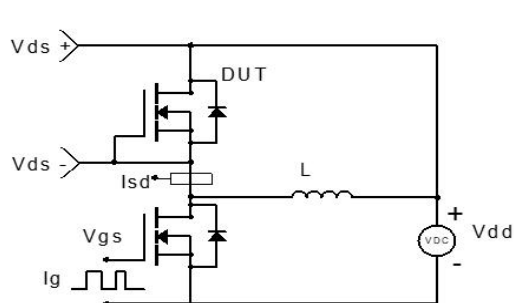
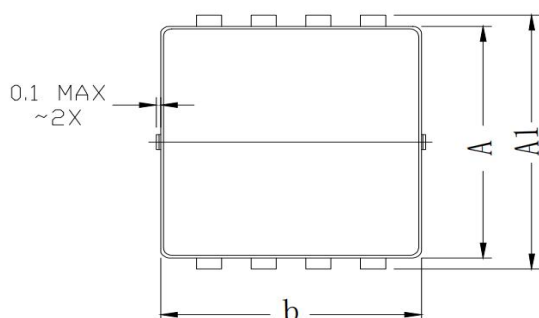
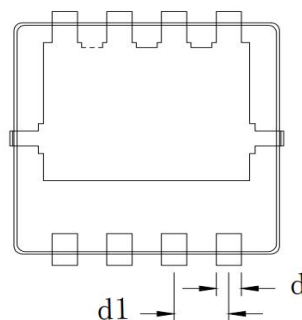
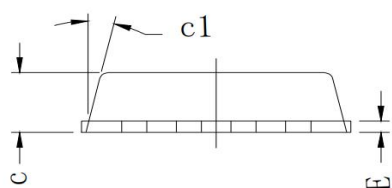


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN3.3x3.3-8L)




COMMON DIMENSION (MM)			
PKG	PDFN 3×3		
Symbol	MIN	MON	MAX
A	3.070	3.100	3.130
A1	3.300	3.400	3.500
b	3.070	3.100	3.130
c	0.770	0.800	0.830
c1	13°		
d	0.300		
d1	0.650		
E	0.152		

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